

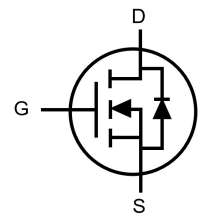
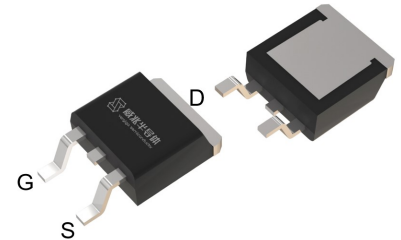
Features

- Enhancement mode
- Low on-resistance $R_{DS(on)}$ @ $V_{GS}=10\text{ V}$
- Fast Switching
- Pb-free lead plating; RoHS compliant



Part ID	Package Type	Marking	Packing
VS5N50ATD	TO-263	5N50ATD	800pcs/Reel

V_{DS}	500	V
$R_{DS(on),TYP}@ V_{GS}=10\text{ V}$	1.45	Ω
I_D	5	A

TO-263


Maximum ratings, at $T_A=25\text{ }^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	500	V
V_{GS}	Gate-Source voltage	± 30	V
I_S	Diode continuous forward current	$T_C=25\text{ }^\circ\text{C}$	5 A
I_D	Continuous drain current @ $V_{GS}=10\text{ V}$	$T_C=25\text{ }^\circ\text{C}$	5 A
		$T_C=100\text{ }^\circ\text{C}$	3 A
I_{DM}	Pulse drain current tested ①	$T_C=25\text{ }^\circ\text{C}$	20 A
I_{DSM}	Continuous drain current @ $V_{GS}=10\text{ V}$	$T_A=25\text{ }^\circ\text{C}$	0.8 A
		$T_A=70\text{ }^\circ\text{C}$	0.7 A
EAS	Avalanche energy, single pulsed ②	375	mJ
P_D	Maximum power dissipation	$T_C=25\text{ }^\circ\text{C}$	63 W
		$T_C=100\text{ }^\circ\text{C}$	25 W
P_{DSM}	Maximum power dissipation ③	$T_A=25\text{ }^\circ\text{C}$	2 W
		$T_A=70\text{ }^\circ\text{C}$	1.6 W
T_{STG}, T_J	Storage and Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	$^\circ\text{C/W}$

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T_j = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	500	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =500V, V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T _j =125°C)	V _{DS} =400V, V _{GS} =0V	--	--	50	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±30V, V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2.5	3.3	3.8	V
R _{DS(ON)}	Drain-Source On-State Resistance ④	V _{GS} =10V, I _D =2.5A	--	1.45	1.6	Ω
		T _j =125°C	--	2.15	--	Ω
Dynamic Electrical Characteristics @ T_j = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =30V, V _{GS} =0V, f=1MHz	425	500	575	pF
C _{oss}	Output Capacitance		45	55	65	pF
C _{rss}	Reverse Transfer Capacitance		--	7	15	pF
R _g	Gate Resistance	f=1MHz	--	2.8	--	Ω
Q _g	Total Gate Charge	V _{DS} =250V, I _D =2.5A, V _{GS} =10V	--	11	--	nC
Q _{gs}	Gate-Source Charge		--	2.7	--	nC
Q _{gd}	Gate-Drain Charge		--	3.4	--	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =250V, I _D =2.5A, R _G =10Ω, V _{GS} =10V	--	8.6	--	ns
t _r	Turn-on Rise Time		--	7.8	--	ns
t _{d(off)}	Turn-Off Delay Time		--	20	--	ns
t _f	Turn-Off Fall Time		--	33	--	ns
Source- Drain Diode Characteristics @ T_j = 25°C (unless otherwise stated)						
V _{SD}	Forward on voltage	I _{SD} =5A, V _{GS} =0V	--	0.9	1.2	V
t _{rr}	Reverse Recovery Time	T _j =25°C, I _{sd} =2.5A, V _{GS} =0V	--	280	--	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs	--	930	--	nC

NOTE:

- ① Repetitive rating; pulse width limited by max junction temperature.
- ② Limited by T_{Jmax}, starting T_J = 25°C, L = 30mH, R_G = 25Ω, I_{AS} = 5A, V_{GS} = 10V. Part not recommended for use above this value
- ③ The power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C.
- ④ Pulse width ≤ 380μs; duty cycle ≤ 2%.

Typical Characteristics

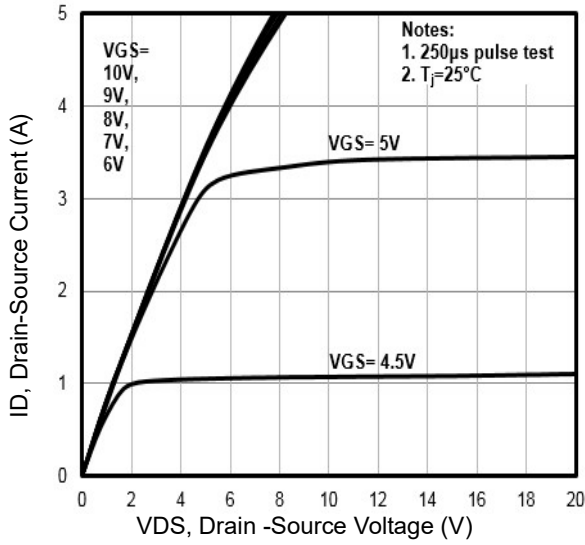


Fig1. Typical Output Characteristics

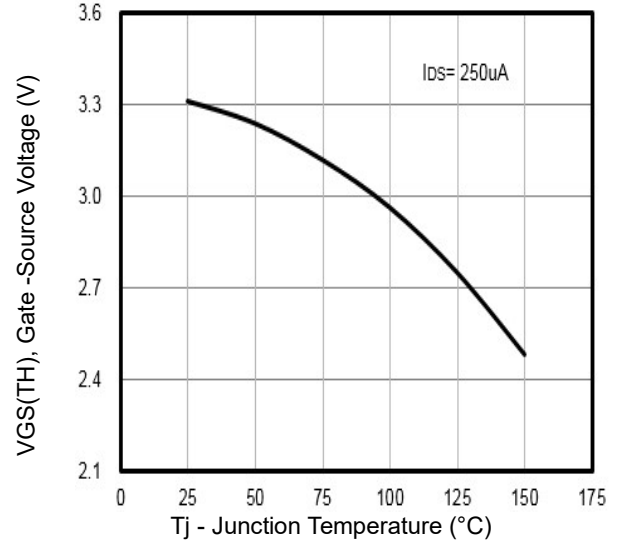


Fig2. $V_{GS(TH)}$ Gate-Source Voltage Vs. T_j

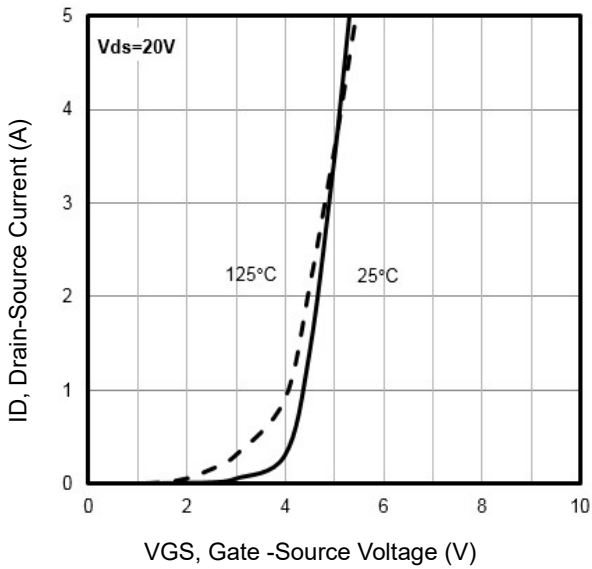


Fig3. Typical Transfer Characteristics

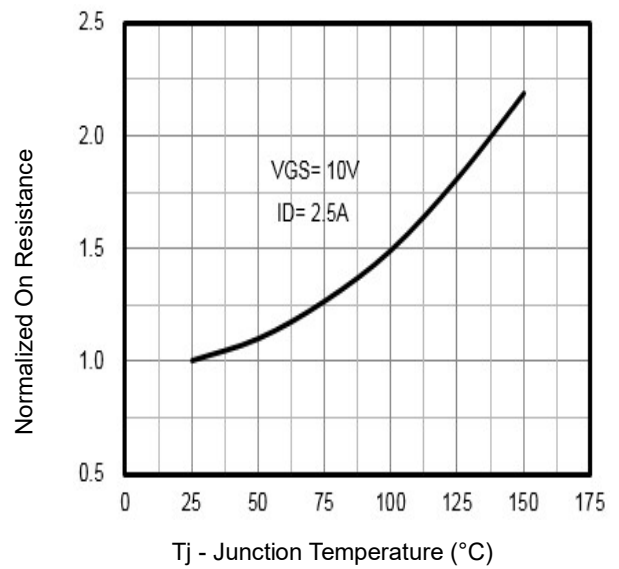


Fig4. Normalized On-Resistance Vs. Temperature

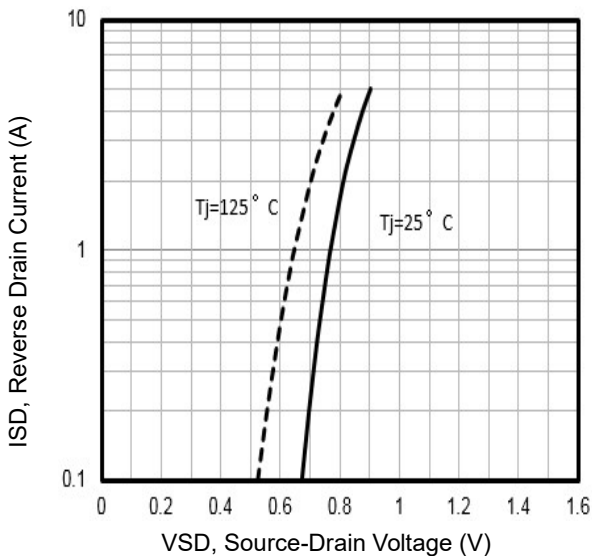


Fig5. Typical Source-Drain Diode Forward Voltage

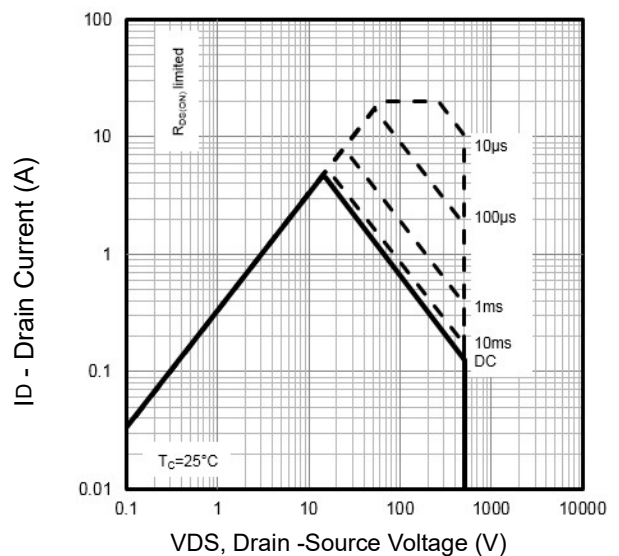


Fig6. Maximum Safe Operating Area

Typical Characteristics

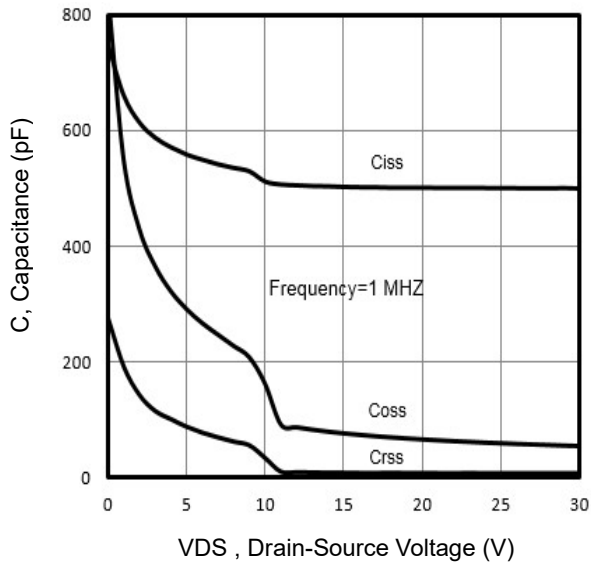


Fig7. Typical Capacitance Vs.Drain-Source Voltage

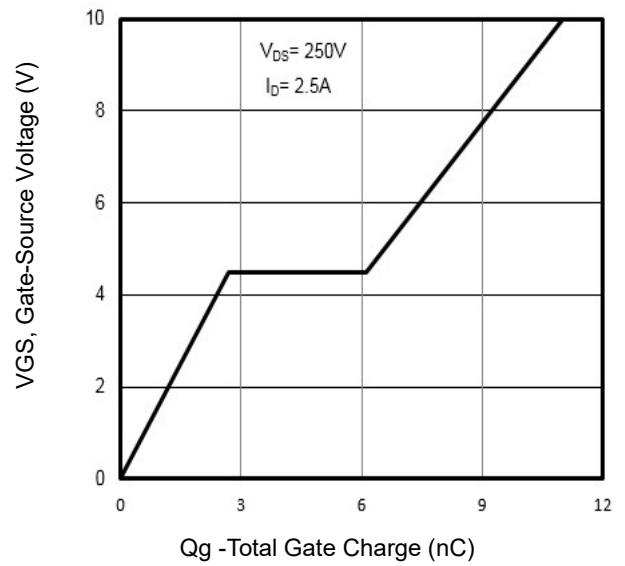


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

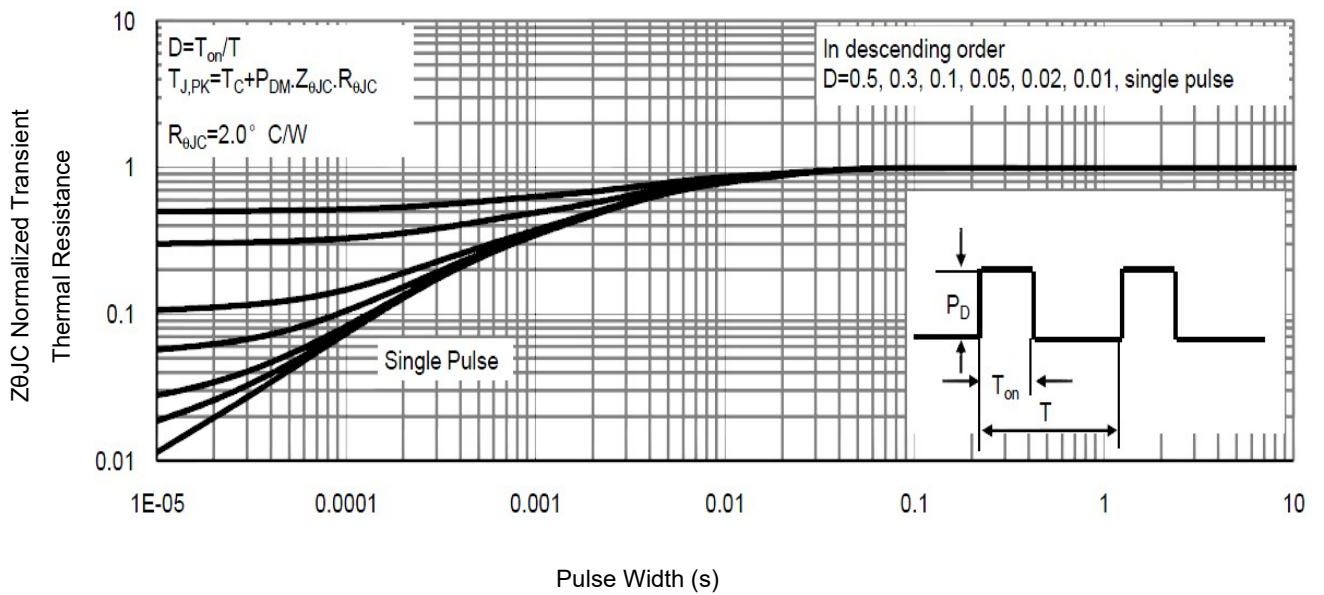


Fig9 . Normalized Maximum Transient Thermal Impedance

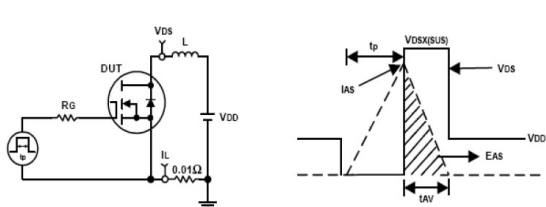


Fig10. Unclamped Inductive Test Circuit and waveforms

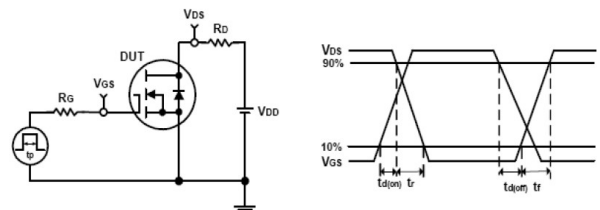
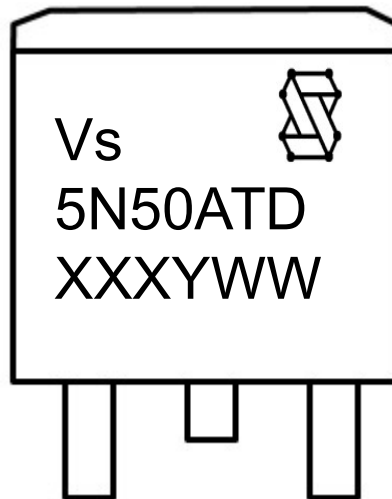


Fig11. Switching Time Test Circuit and waveforms

Marking Information


1st line: Vergiga Code (Vs), Vergiga Logo

2nd line: Part Number (5N50ATD)

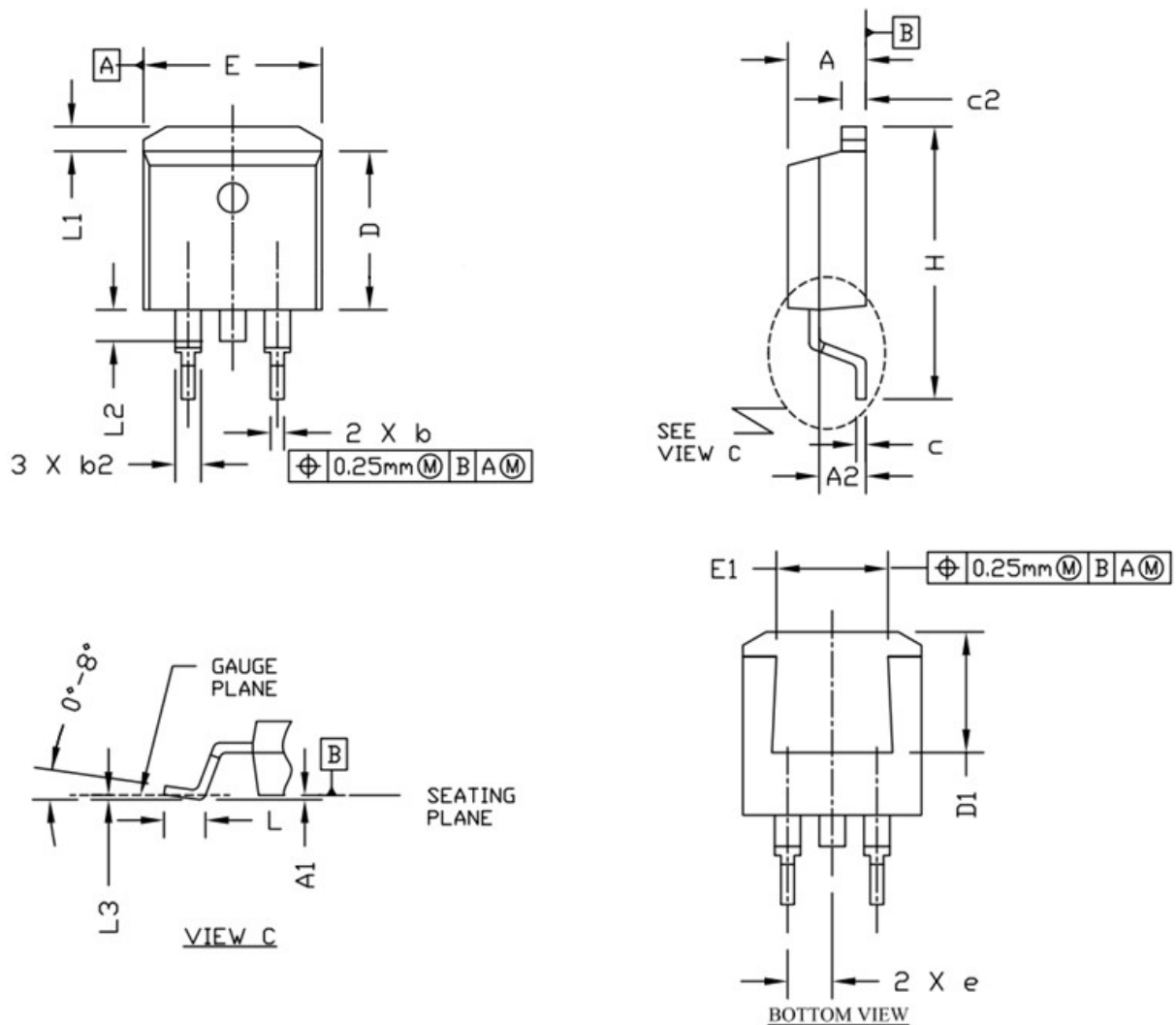
3rd line: Date code (XXXYWW)

XXX: Wafer Lot Number Code , code changed with Lot Number

Y: Year Code , refer to table below

WW: Week Code (01 to 53)

Code	C	D	E	F	G	H	J	K	L	M	N	P	Q	R	S	T
Year	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030

TO-263 Package Outline Data


Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	4.400	4.570	4.700
A1	0.000	0.100	0.200
A2	2.300	2.400	2.500
b	0.700	0.800	0.900
b2	1.200	1.270	1.360
c	0.381	0.500	0.737
c2	1.220	1.300	1.350
D	8.600	9.200	9.300
D1	6.860		
e	2.540 BSC		
E	9.780	9.880	10.260
E1	6.225		
H	14.700	15.100	15.500
L	2.000	2.550	2.750
L1	1.000	1.200	1.400
L2	1.300	1.600	1.700
L3	0.255 BSC		

Notes:

1. Refer to JEDEC TO-263 variation AB
2. Dimension "D" & "E" do NOT include mold flash, mold flash shall not exceed 0.127mm per side.

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